



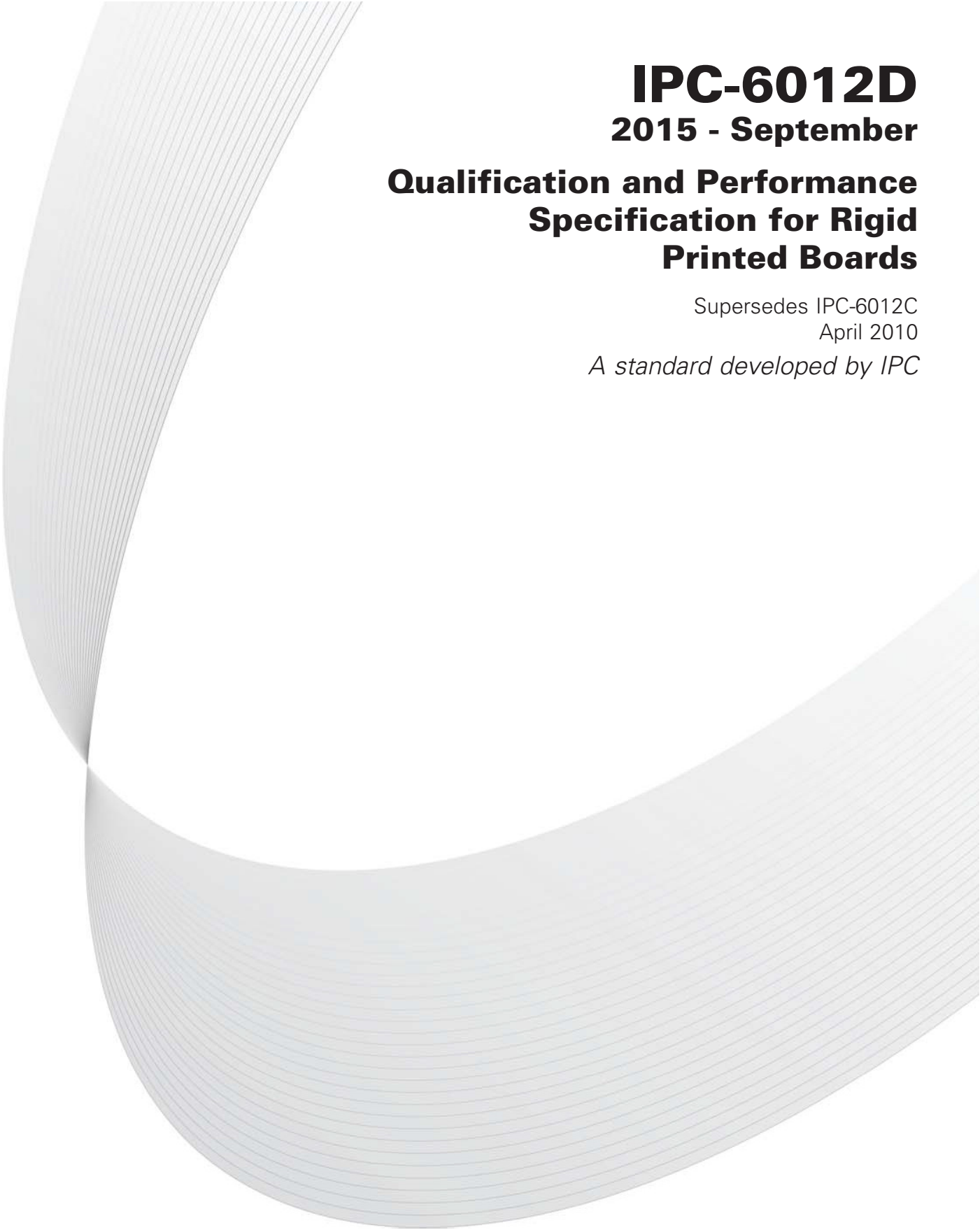
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Qualification and Performance Specification for Rigid Printed Boards

Supersedes IPC-6012C
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IPC-6012D

Qualification and Performance Specification for Rigid Printed Boards

Developed by the Rigid Printed Board Performance Specifications Task Group (D-33a) of the Rigid Printed Board Committee (D-30) of IPC

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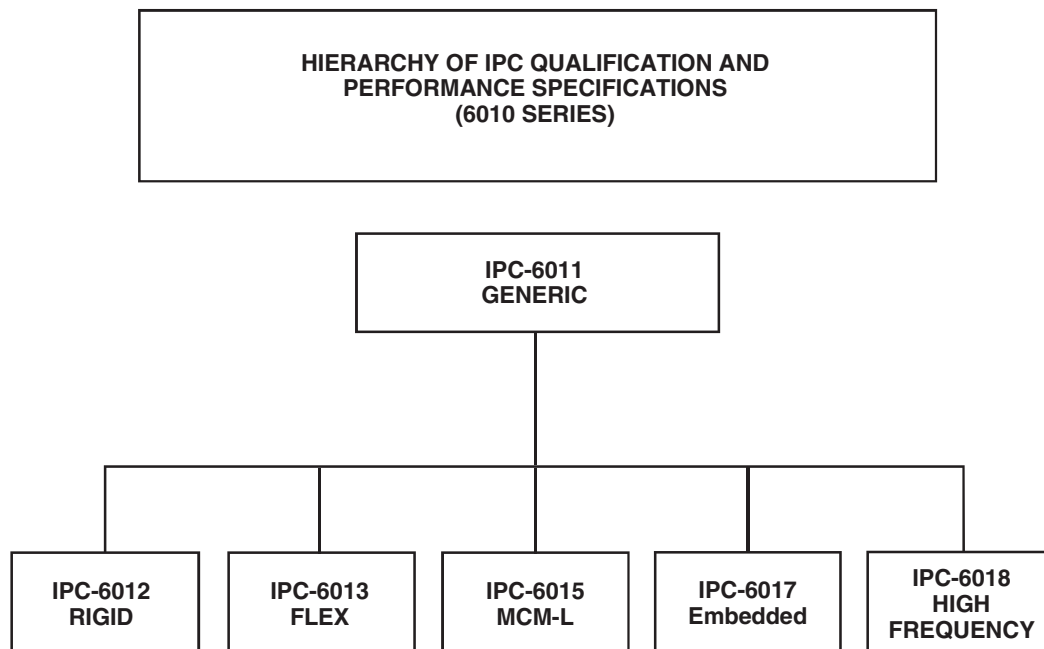
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FOREWORD

This specification is intended to provide information on the detailed performance criteria of rigid printed boards. It supersedes IPC-6012C and was developed as a revision to those documents. The information contained herein is also intended to supplement the generic requirements identified in IPC-6011. When used together, these documents should lead both manufacturer and customer to consistent terms of acceptability.

IPC's documentation strategy is to provide distinct documents that focus on specific aspects of electronic packaging issues. In this regard, document sets are used to provide the total information related to a particular electronic packaging topic. A document set is identified by a four digit number that ends in zero (0) (i.e., IPC-6010).

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As technology changes, a performance specification will be updated, or new focus specifications will be added to the document set. The IPC invites input on the effectiveness of the documentation and encourages user response through completion of "Suggestions for Improvement" forms located at the end of each document.

Acknowledgment

Any document involving a complex technology draws material from a vast number of sources across many continents. While the principal members of the Rigid Printed Board Performance Specifications Task Group (D-33a) of the Rigid Printed Board Committee (D-30) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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